

Features

- Ultra-Small Surface Mount Package
- Ideally Suited for Automated Insertion
- For switching and AF Amplifier Application
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)**
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP capable (Note 4)

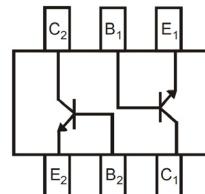
Mechanical Data

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — Matte Tin Finish. Solderable per MIL-STD-202, Method 208 (e3)
- Weight: 0.006 grams (approximate)

SOT363



Top View



Device Schematic
Top View

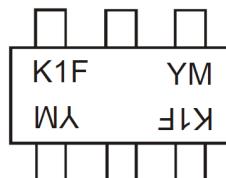
Ordering Information (Notes 4 & 5)

Part Number	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
BC847BS-7-F	AEC-Q101	K1F	7	8	3,000
BC847BSQ-7-F	Automotive	K1F	7	8	3,000
BC847BS-13-F	AEC-Q101	K1F	13	8	10,000

Notes:

- No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified.
- For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



K1F = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: Y = 2011)
 M = Month (ex: 9 = September)

Date Code Key

Year	2010	2011	2012	2013	2014	2015	2016	2017				
Code	X	Y	Z	A	B	C	D	E				
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@ $T_A = +25^\circ\text{C}$ unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	50	V
Collector-Emitter Voltage	V_{CEO}	45	V
Emitter-Base Voltage	V_{EBO}	6	V
Collector Current	I_C	100	mA
Peak Collector Current	I_{CM}	200	mA
Peak Base Current	I_{BM}	200	mA

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$ unless otherwise specified.)

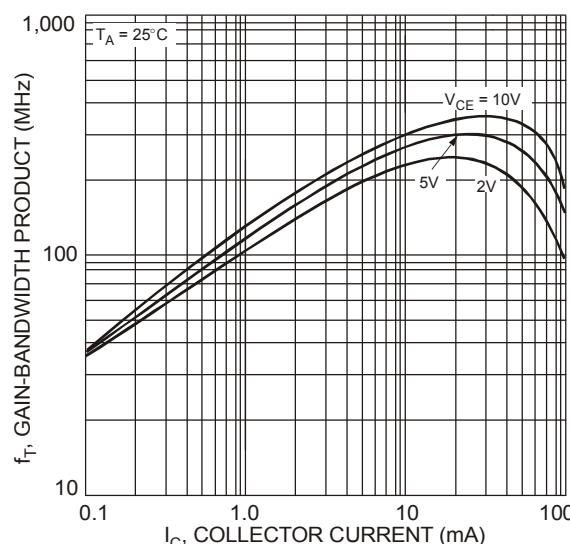
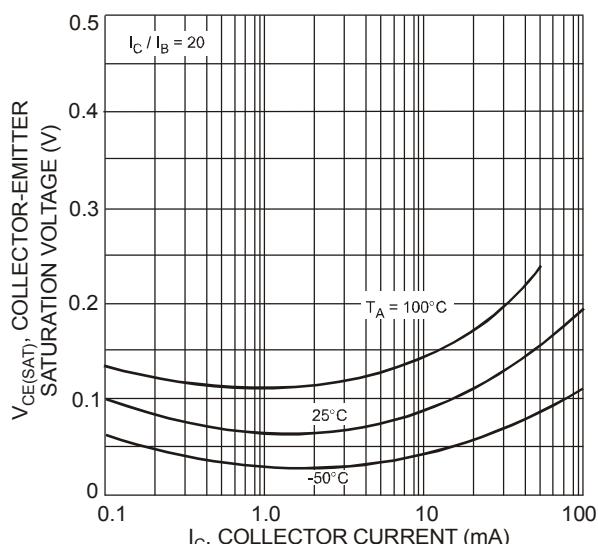
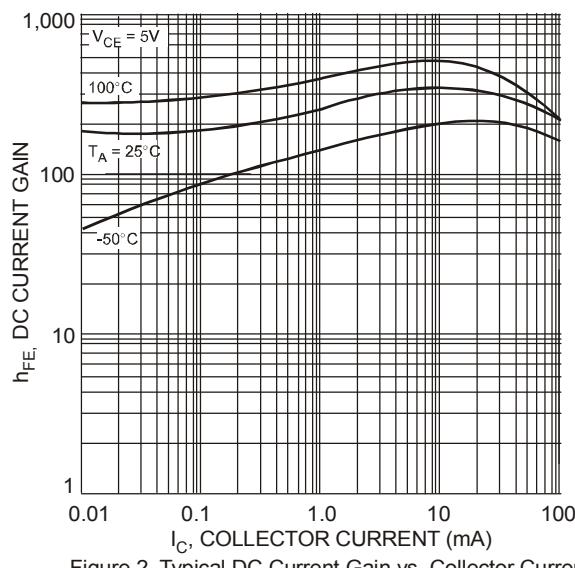
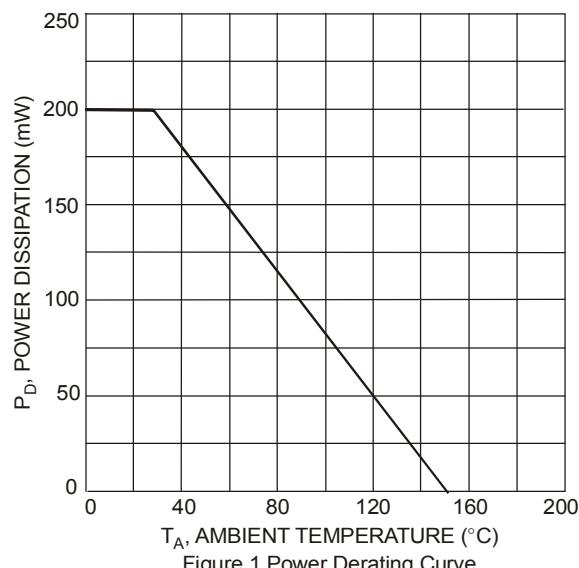
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P_D	200	mW
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	625	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	°C

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$ unless otherwise specified.)

Characteristic (Note 7)	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV_{CBO}	50	—	—	V	$I_C = 100\mu\text{A}, I_B = 0$
Collector-Emitter Breakdown Voltage	BV_{CEO}	45	—	—	V	$I_C = 10\text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	BV_{EBO}	6	—	—	V	$I_E = 100\mu\text{A}, I_C = 0$
DC Current Gain	h_{FE}	200	—	450	—	$V_{CE} = 5.0\text{V}, I_C = 2.0\text{mA}$
Collector-Emitter Saturation Voltage	$V_{CE(\text{sat})}$	—	—	100 400	mV	$I_C = 10\text{mA}, I_B = 0.5\text{mA}$ $I_C = 100\text{mA}, I_B = 5.0\text{mA}$
Base-Emitter Saturation Voltage	$V_{BE(\text{sat})}$	—	755	—	mV	$I_C = 10\text{mA}, I_B = 0.5\text{mA}$
Base-Emitter Voltage	$V_{BE(\text{on})}$	580	665	700	mV	$V_{CE} = 5.0\text{V}, I_C = 2.0\text{mA}$
Collector-Cutoff Current	I_{CBO}	—	—	20 5.0	nA μA	$V_{CB} = 40\text{V}$ $V_{CB} = 40\text{V}, T_A = +125^\circ\text{C}$
Emitter-Cutoff Current	I_{EBO}	—	—	100	nA	$V_{EB} = 5.0\text{V}, I_C = 0$
Gain Bandwidth Product	f_T	100	—	—	MHz	$V_{CE} = 5.0\text{V}, I_C = 10\text{mA}, f = 100\text{MHz}$
Collector-Base Capacitance	C_{CBO}	—	2.0	3.0	pF	$V_{CB} = 10\text{V}, f = 1.0\text{MHz}$
Emitter-Base Capacitance	C_{EBO}	—	11	—	pF	$V_{EB} = 0.5\text{V}, f = 1.0\text{MHz}$

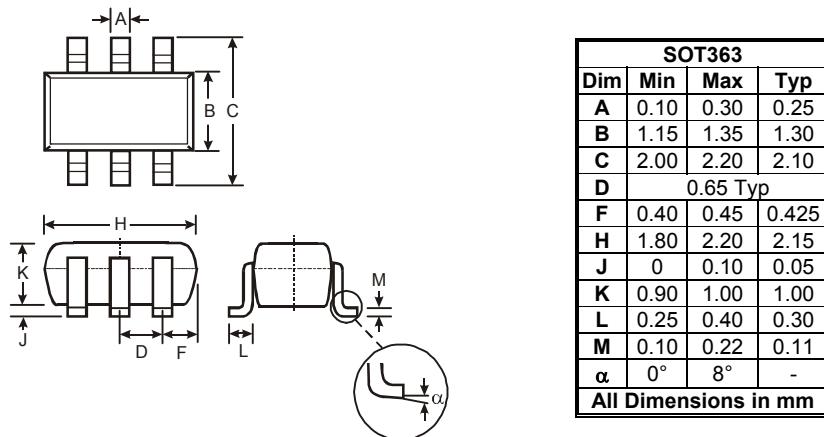
Notes: 6. For the device mounted on minimum recommended pad layout FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
7. Short duration pulse test used to minimize self-heating effect.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$ unless otherwise specified.)



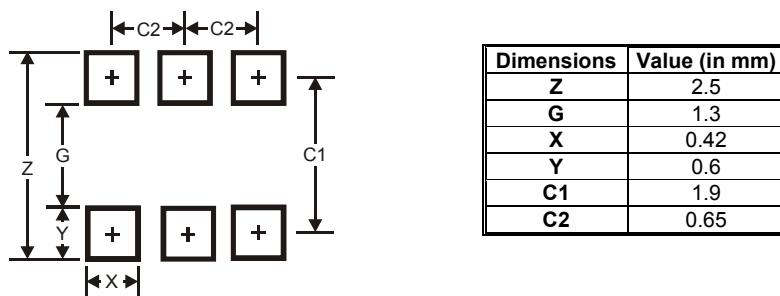
Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



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